



GreenMOS™

## OSG50R1K5xF\_Datasheet



# Enhancement Mode N-Channel Power MOSFET

## Features

- ◆ Low  $R_{DS(on)}$  & FOM
- ◆ Excellent low switching loss
- ◆ Excellent stability and uniformity
- ◆ Easy to drive

## Applications

- ◆ Lighting
- ◆ Hard switching PWM
- ◆ Server power supply
- ◆ Charger
- ◆ Lighting

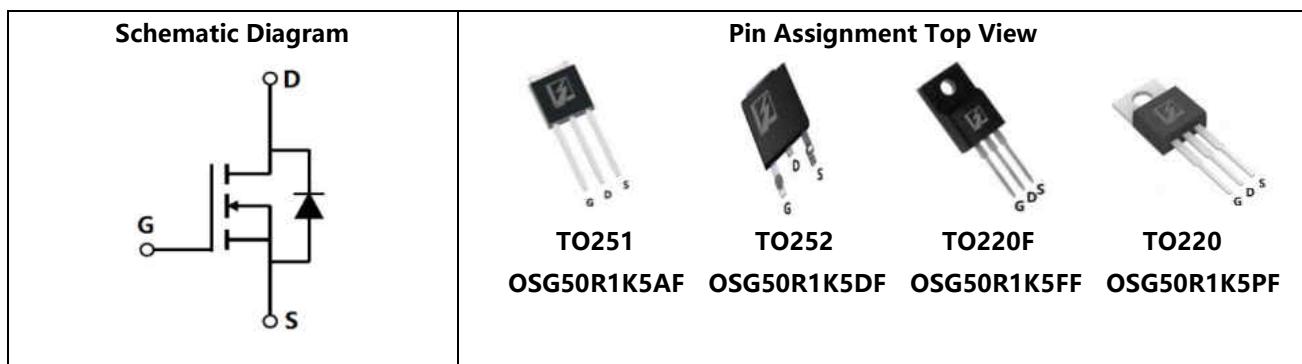


## ■ General Description

OSG50R1K5xF use advanced GreenMOS™ technology to provide low  $R_{DS(ON)}$ , low gate charge, fast switching and excellent avalanche characteristics. This device is suitable for active power factor correction and switching mode power supply applications.

|                                       |              |
|---------------------------------------|--------------|
| ◆ $V_{DS, min@Tjmax}$                 | 550 V        |
| ◆ $I_D, pulse$                        | 9 A          |
| ◆ $R_{DS(ON)}, max @ VGS=10\text{ V}$ | 1.5 $\Omega$ |
| ◆ $Q_g$                               | 4.84 nC      |

## ■ Schematic and Package Information



## ■ Absolute Maximum Ratings at $T_j=25^\circ\text{C}$ unless otherwise noted

| PARAMETER   | SYMBOL         | VALUE      | UNIT             |
|---|----------------|------------|------------------|
| Drain source voltage  | $V_{DS}$       | 500        | V                |
| Gate source voltage   | $V_{GS}$       | $\pm 30$   | V                |
| Continuous drain current <sup>1)</sup> , $T_C=25\text{ }^\circ\text{C}$                 | $I_D$          | 3          | A                |
| Continuous drain current <sup>1)</sup> , $T_C=100\text{ }^\circ\text{C}$                |                | 1.9        |                  |
| Pulsed drain current <sup>2)</sup> , $T_C=25\text{ }^\circ\text{C}$                     | $I_D, pulse$   | 9          | A                |
| Power dissipation <sup>3)</sup> for TO251, TO252, TO220, $T_C=25\text{ }^\circ\text{C}$ | $P_D$          | 20         | W                |
| Power dissipation <sup>3)</sup> for TO220F, $T_C=25\text{ }^\circ\text{C}$              |                | 18         |                  |
| Single pulsed avalanche energy <sup>5)</sup>  | $E_{AS}$       | 60         | mJ               |
| MOSFET dv/dt ruggedness, $V_{DS}=0\ldots 400\text{ V}$                                  | dv/dt          | 50         | V/ns             |
| Reverse diode dv/dt, $V_{DS}=0\ldots 400\text{ V}$ , $I_{SD} \leq I_D$                  | dv/dt          | 15         | V/ns             |
| Operation and storage temperature   | $T_{stg}, T_j$ | -55 to 150 | $^\circ\text{C}$ |



## ■ Thermal Characteristics

| PARAMETER  | SYMBOL          | VALUE             |        | UNIT |
|--|-----------------|-------------------|--------|------|
|  |                 | TO251/TO252/TO220 | TO220F |      |
| Thermal resistance, junction-case                  | $R_{\theta JC}$ | 6.25              | 6.94   | °C/W |
| Thermal resistance, junction-ambient <sup>4)</sup> | $R_{\theta JA}$ | 62                | 62.5   | °C/W |

## ■ Electrical Characteristics at $T_j=25$ °C unless otherwise specified

| PARAMETER                        | SYMBOL       | MIN. | TYP. | MAX. | UNIT | TEST CONDITION                           |
|----------------------------------|--------------|------|------|------|------|--|
| Drain-source breakdown voltage   | $BV_{DSS}$   | 500  |      |      | V    | $V_{GS}=0$ V, $I_D=250$ μA               |
|                                  |              | 550  | 630  |      |      | $V_{GS}=0$ V, $I_D=250$ μA, $T_j=150$ °C |
| Gate threshold voltage           | $V_{GS(th)}$ | 2.9  |      | 3.9  | V    | $V_{DS}=V_{GS}$ , $I_D=250$ μA           |
| Drain-source on-state resistance | $R_{DS(ON)}$ |      | 1.3  | 1.5  | Ω    | $V_{GS}=10$ V, $I_D=1.5$ A               |
|                                  |              |      | 3    |      |      | $V_{GS}=10$ V, $I_D=1.5$ A, $T_j=150$ °C |
| Gate-source leakage current      | $I_{GSS}$    |      |      | 100  | nA   | $V_{GS}=30$ V                            |
|                                  |              |      |      | -100 |      | $V_{GS}=-30$ V                           |
| Drain-source leakage current     | $I_{DSS}$    |      |      | 1    | μA   | $V_{DS}=500$ V, $V_{GS}=0$ V             |

## ■ Dynamic Characteristics

| PARAMETER                    | SYMBOL       | MIN. | TYP.  | MAX. | UNIT | TEST CONDITION   |
|------------------------------|--------------|------|-------|------|------|--|
| Input capacitance            | $C_{iss}$    |      | 130.6 |      | pF   | $V_{GS}=0$ V,<br>$V_{DS}=50$ V,<br>$f=1$ MHz                 |
| Output capacitance           | $C_{oss}$    |      | 51.7  |      | pF   |  |
| Reverse transfer capacitance | $C_{rss}$    |      | 1.0   |      | pF   |  |
| Turn-on delay time           | $t_{d(on)}$  |      | 15.3  |      | ns   | $V_{GS}=10$ V,<br>$V_{DS}=400$ V,<br>$R_G=2$ Ω,<br>$I_D=2$ A |
| Rise time                    | $t_r$        |      | 4.8   |      | ns   |  |
| Turn-off delay time          | $t_{d(off)}$ |      | 22.0  |      | ns   |  |
| Fall time                    | $t_f$        |      | 7.6   |      | ns   |  |



## ■ Gate Charge Characteristics

| PARAMETER            | SYMBOL        | MIN. | TYP. | MAX. | UNIT | TEST CONDITION  |
|----------------------|---------------|------|------|------|------|---|
| Total gate charge    | $Q_g$         |      | 4.84 |      | nC   | $I_D=2\text{ A}$ ,<br>$V_{DS}=400\text{ V}$ ,<br>$V_{GS}=10\text{ V}$ |
| Gate-source charge   | $Q_{gs}$      |      | 0.87 |      | nC   |   |
| Gate-drain charge    | $Q_{gd}$      |      | 1.93 |      | nC   |   |
| Gate plateau voltage | $V_{plateau}$ |      | 5.8  |      | V    |   |

## ■ Body Diode Characteristics

| PARAMETER                     | SYMBOL    | MIN. | TYP.  | MAX. | UNIT          | TEST CONDITION   |
|-------------------------------|-----------|------|-------|------|---------------|--|
| Diode forward current         | $I_S$     |      |       | 3    | A             | $V_{GS} < V_{th}$  |
| Pulsed source current         | $I_{SP}$  |      |       | 9    |               |  |
| Diode forward voltage         | $V_{SD}$  |      |       | 1.4  | V             | $I_S=3\text{ A}, V_{GS}=0\text{ V}$                                      |
| Reverse recovery time         | $t_{rr}$  |      | 146.1 |      | ns            | $V_R=400\text{ V}, I_S=2\text{ A}$ ,<br>$di/dt=100\text{ A}/\mu\text{s}$ |
| Reverse recovery charge       | $Q_{rr}$  |      | 0.7   |      | $\mu\text{C}$ |  |
| Peak reverse recovery current | $I_{rrm}$ |      | 10.1  |      | A             |  |

## ■ Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3)  $P_d$  is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of  $R_{\theta JA}$  is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with  $T_a=25\text{ }^\circ\text{C}$ .
- 5)  $V_{DD}=50\text{ V}$ ,  $R_G=50\text{ }\Omega$ ,  $L=60\text{ mH}$ , starting  $T_j=25\text{ }^\circ\text{C}$ .



## ■ Electrical Characteristics Diagrams

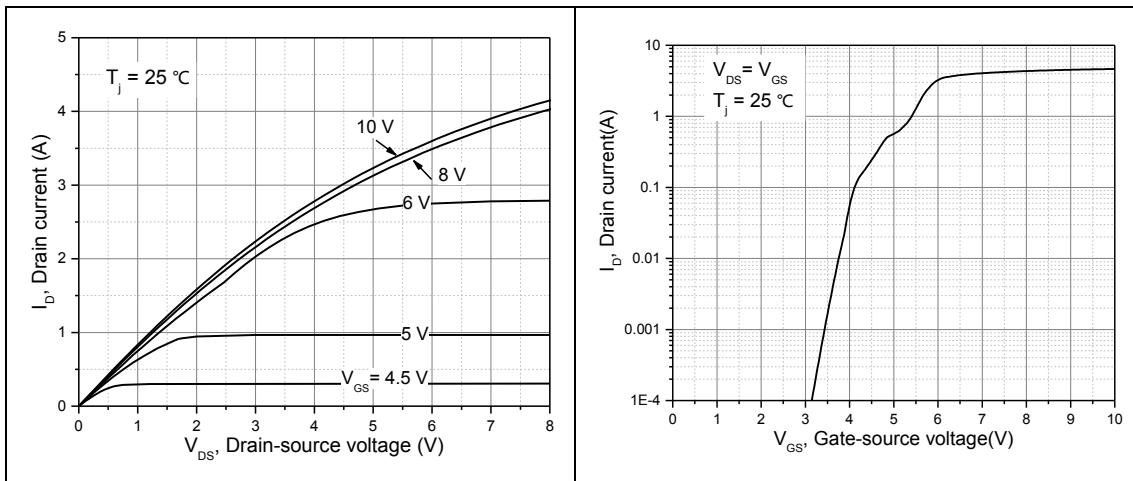


Figure 1, Typ. output characteristics

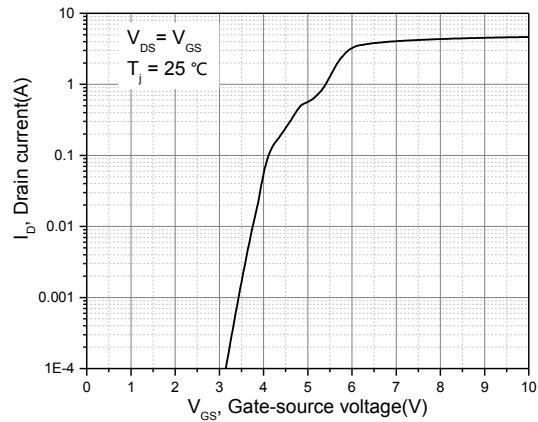


Figure 2, Typ. transfer characteristics

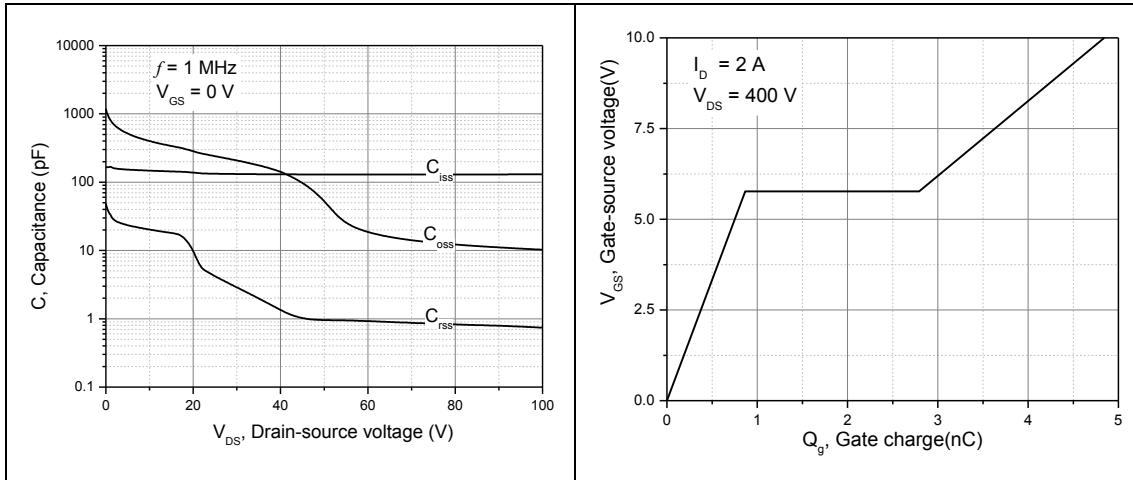


Figure 3, Typ. capacitances

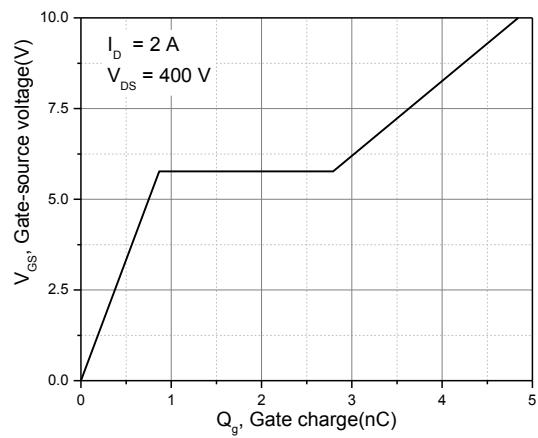


Figure 4, Typ. gate charge

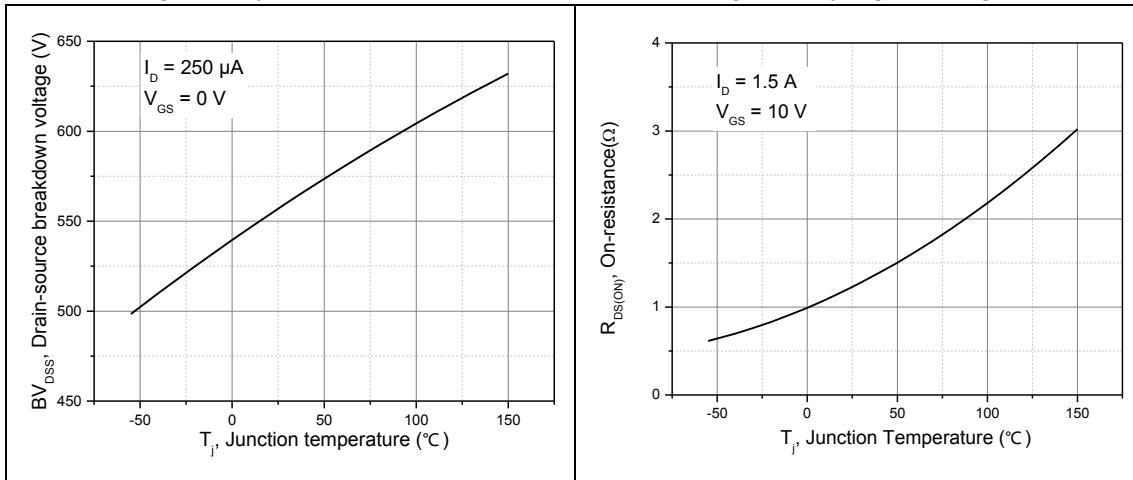


Figure 5, Drain-source breakdown voltage

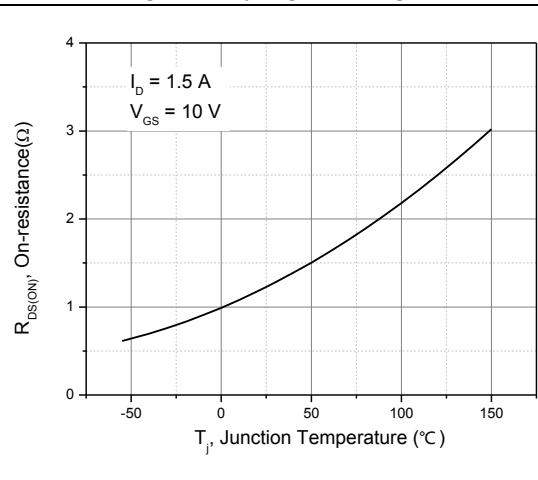


Figure 6, Drain-source on-state resistance

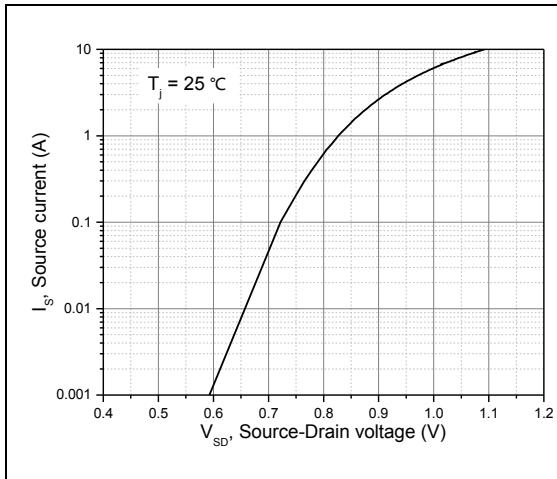


Figure 7, Forward characteristic of body diode

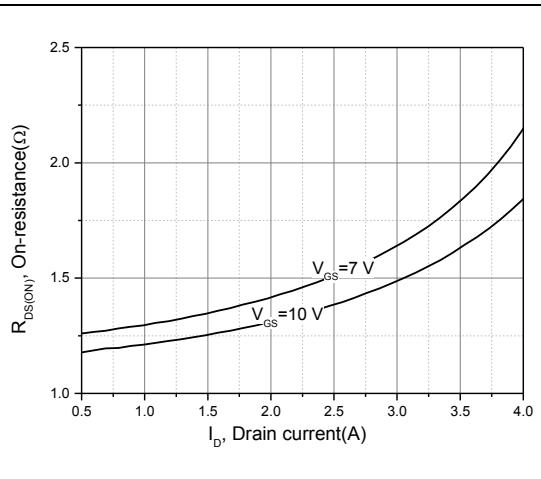


Figure 8, Drain-source on-state resistance

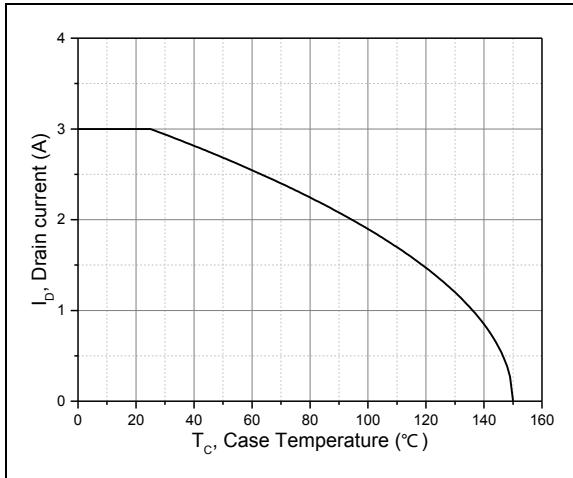


Figure 9, Drain current

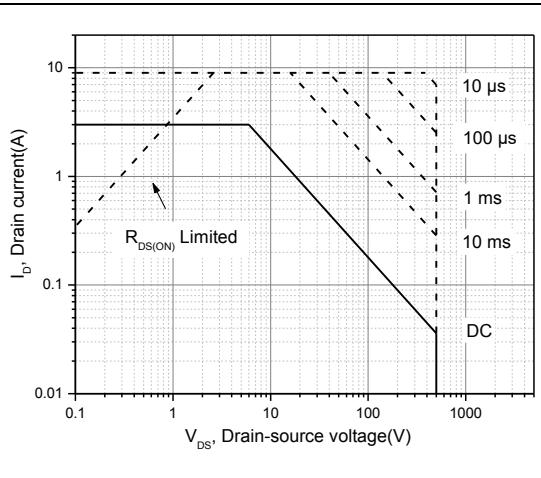


Figure 10, Safe operation area for TO220F  
 $T_C=25\text{ }^{\circ}\text{C}$

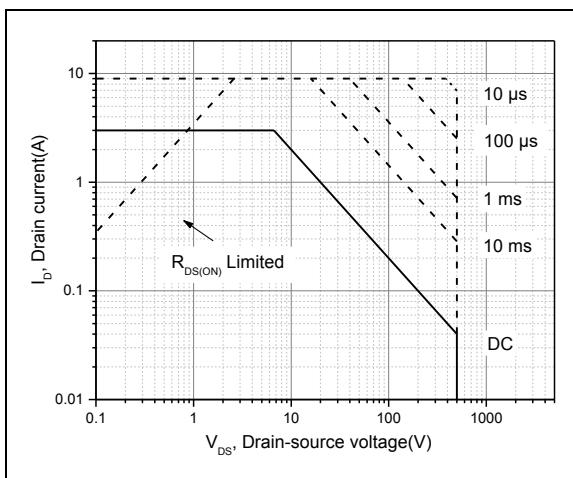


Figure 10, Safe operation area for  
TO251/TO252/TO220  $T_C=25\text{ }^{\circ}\text{C}$



## ■ Test circuits and waveforms

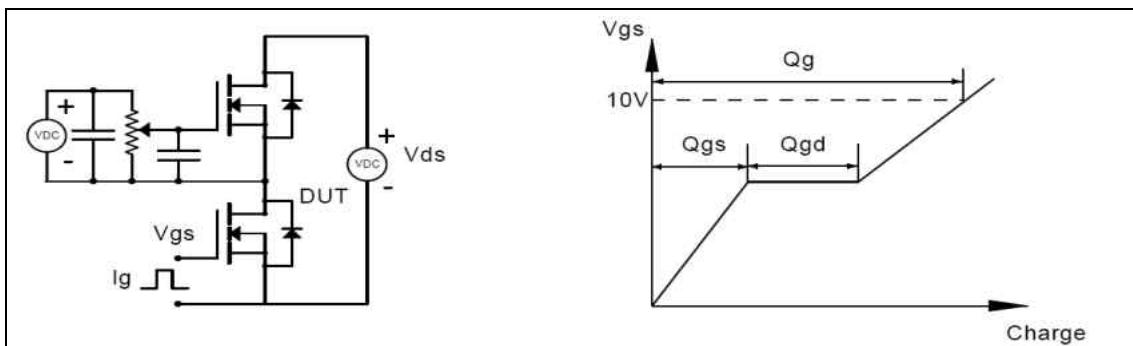


Figure 1, Gate charge test circuit &amp; waveform

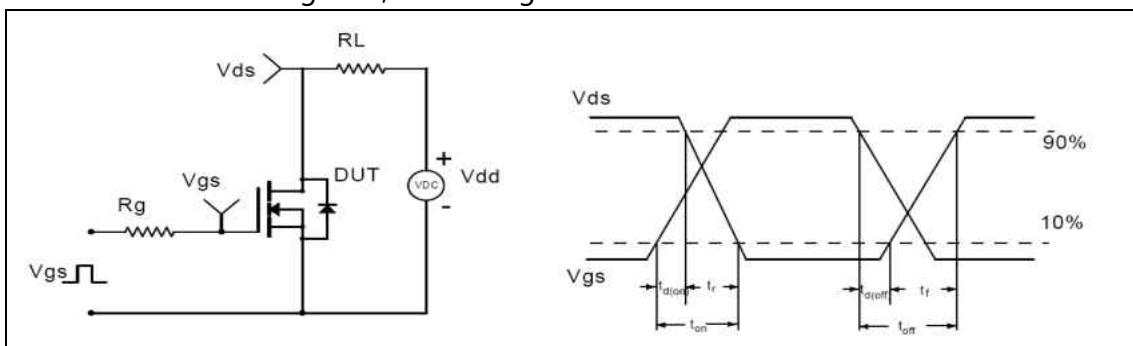


Figure 2, Switching time test circuit &amp; waveforms

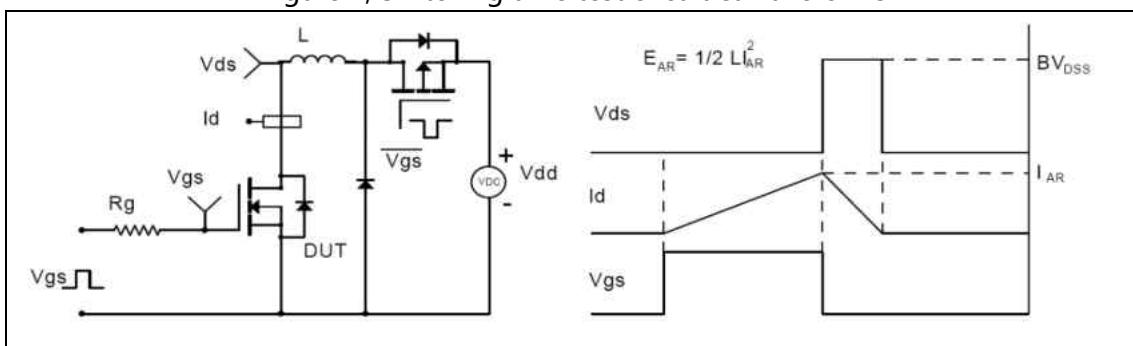


Figure 3, Unclamped inductive switching (UIS) test circuit &amp; waveforms

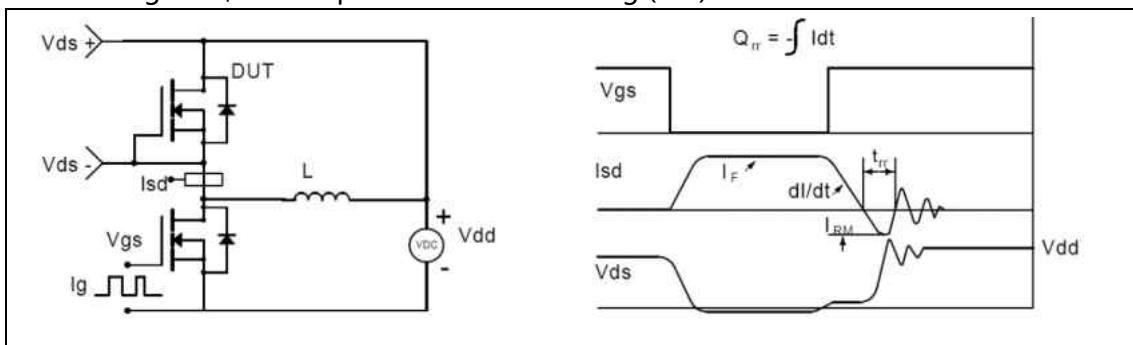
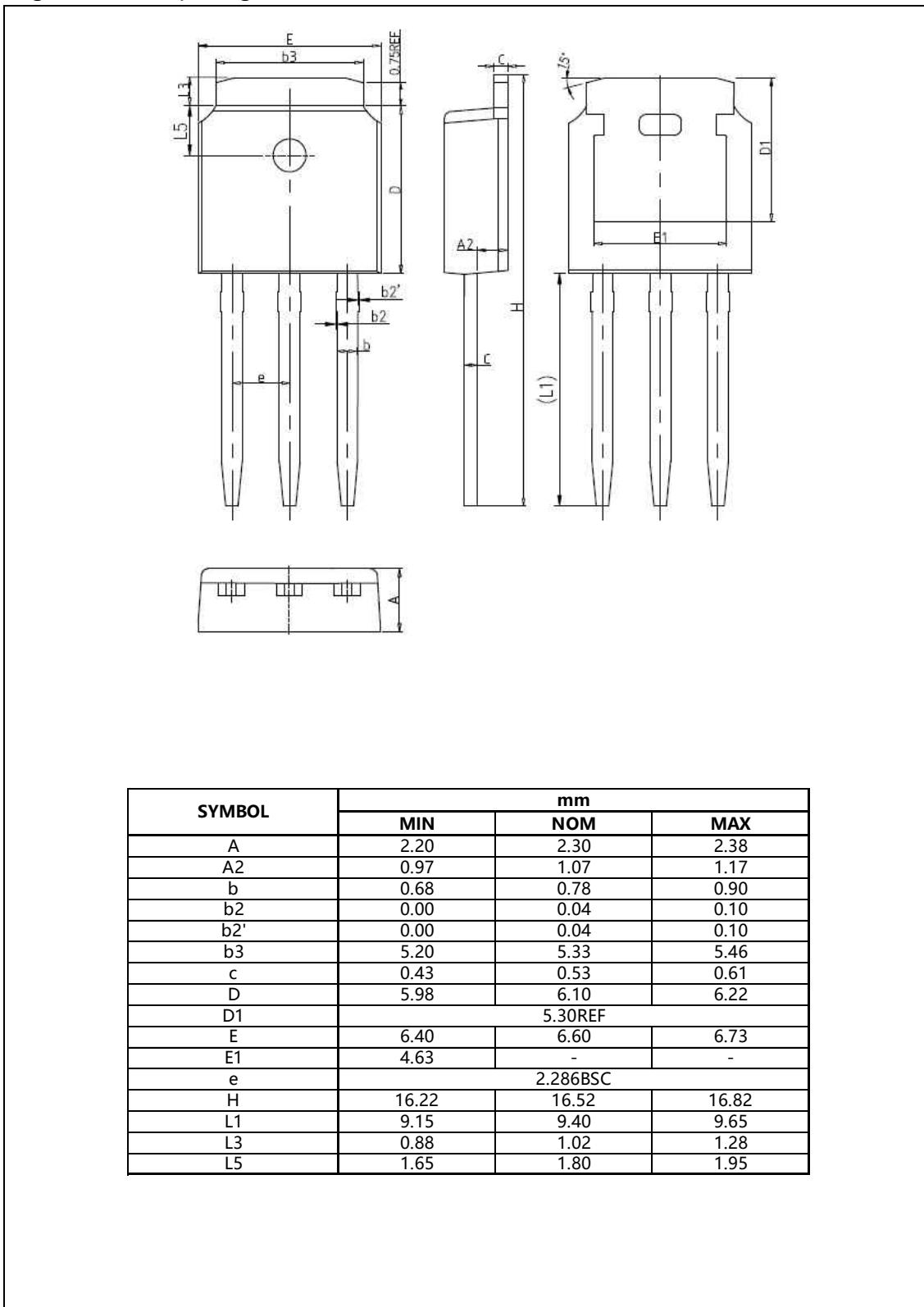


Figure 4, Diode reverse recovery test circuit &amp; waveforms



## ■ Package Information

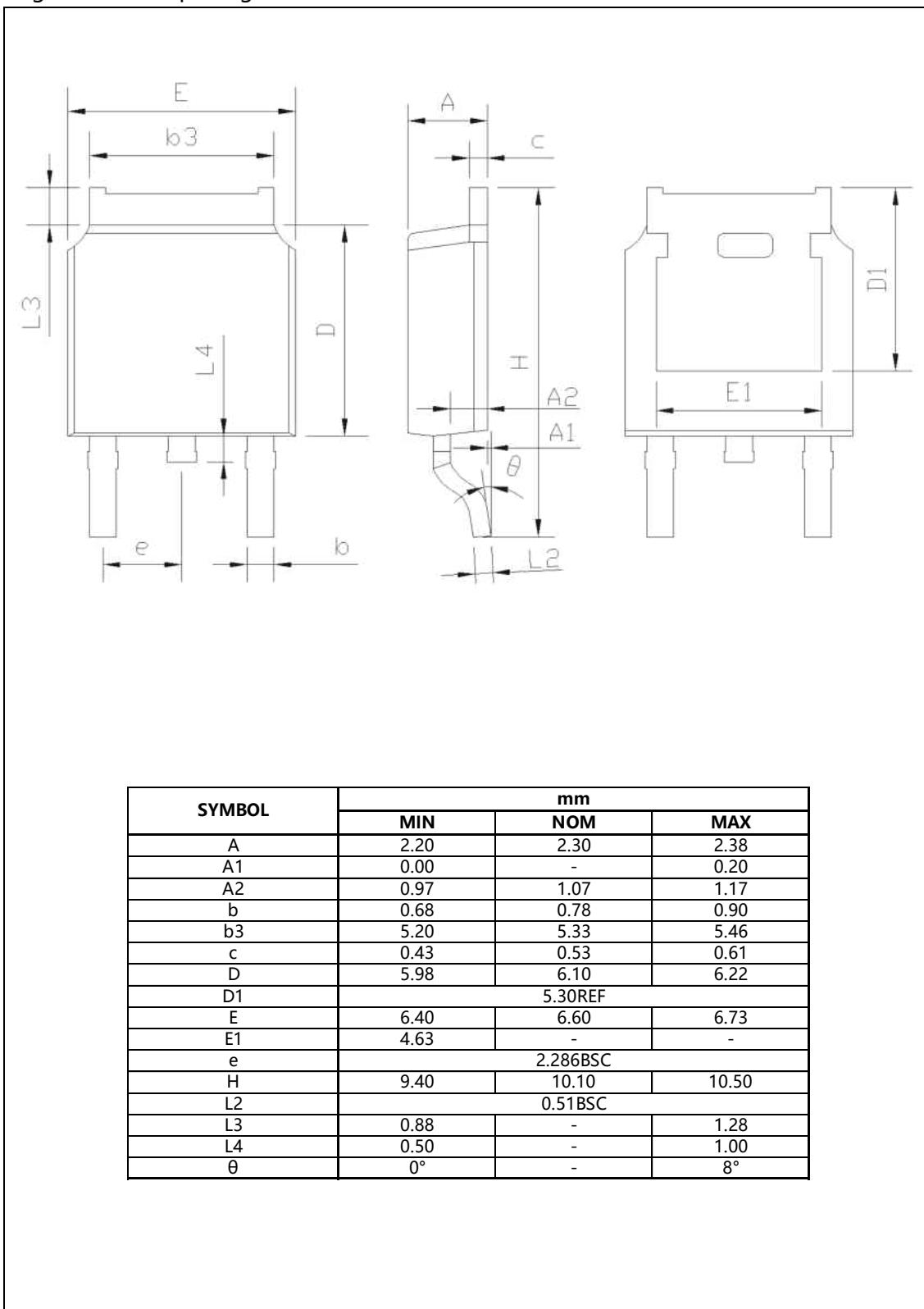
Figure1, TO251 package outline dimension





## ■ Package Information

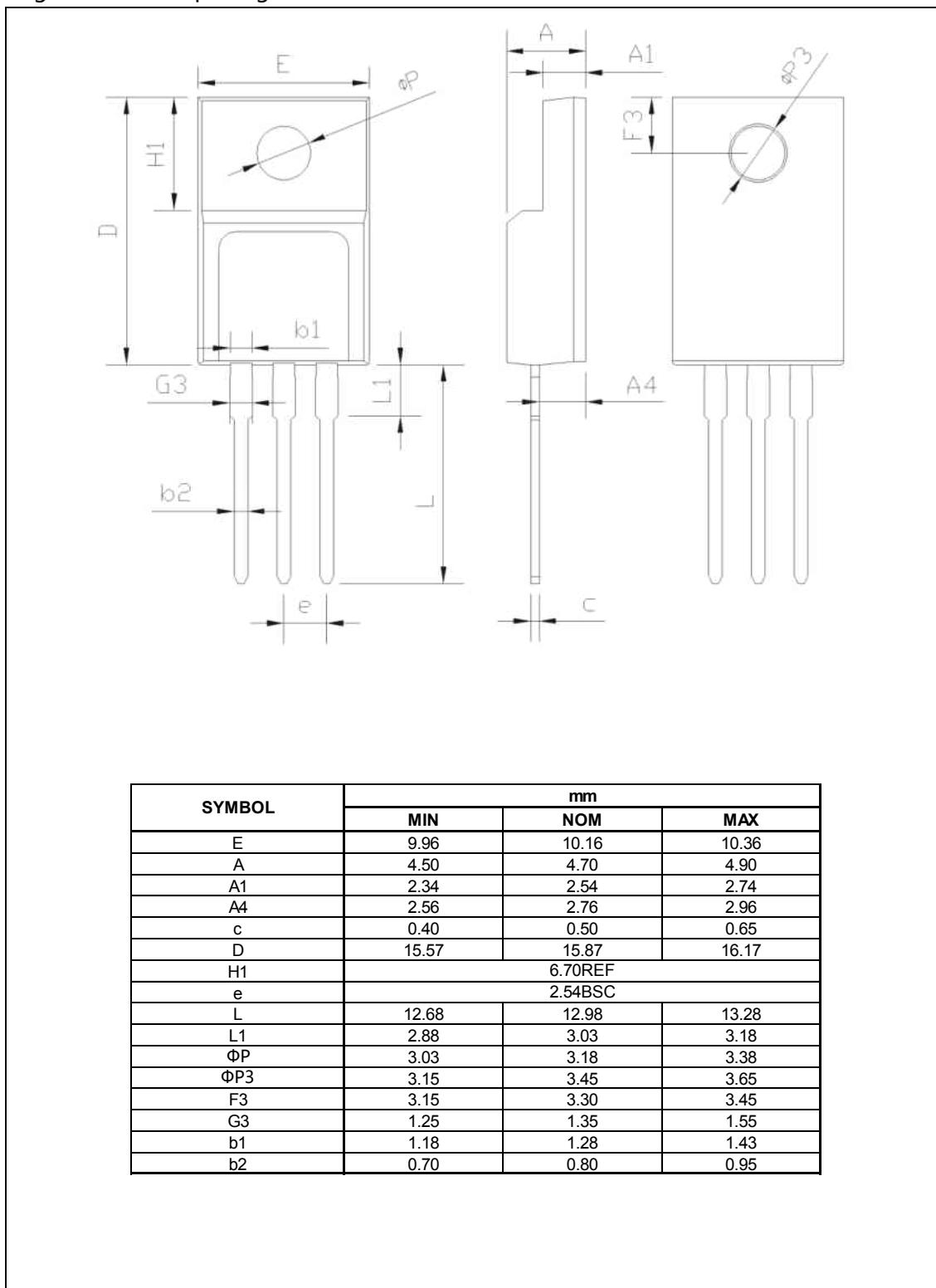
Figure2, TO252 package outline dimension





## ■ Package Information

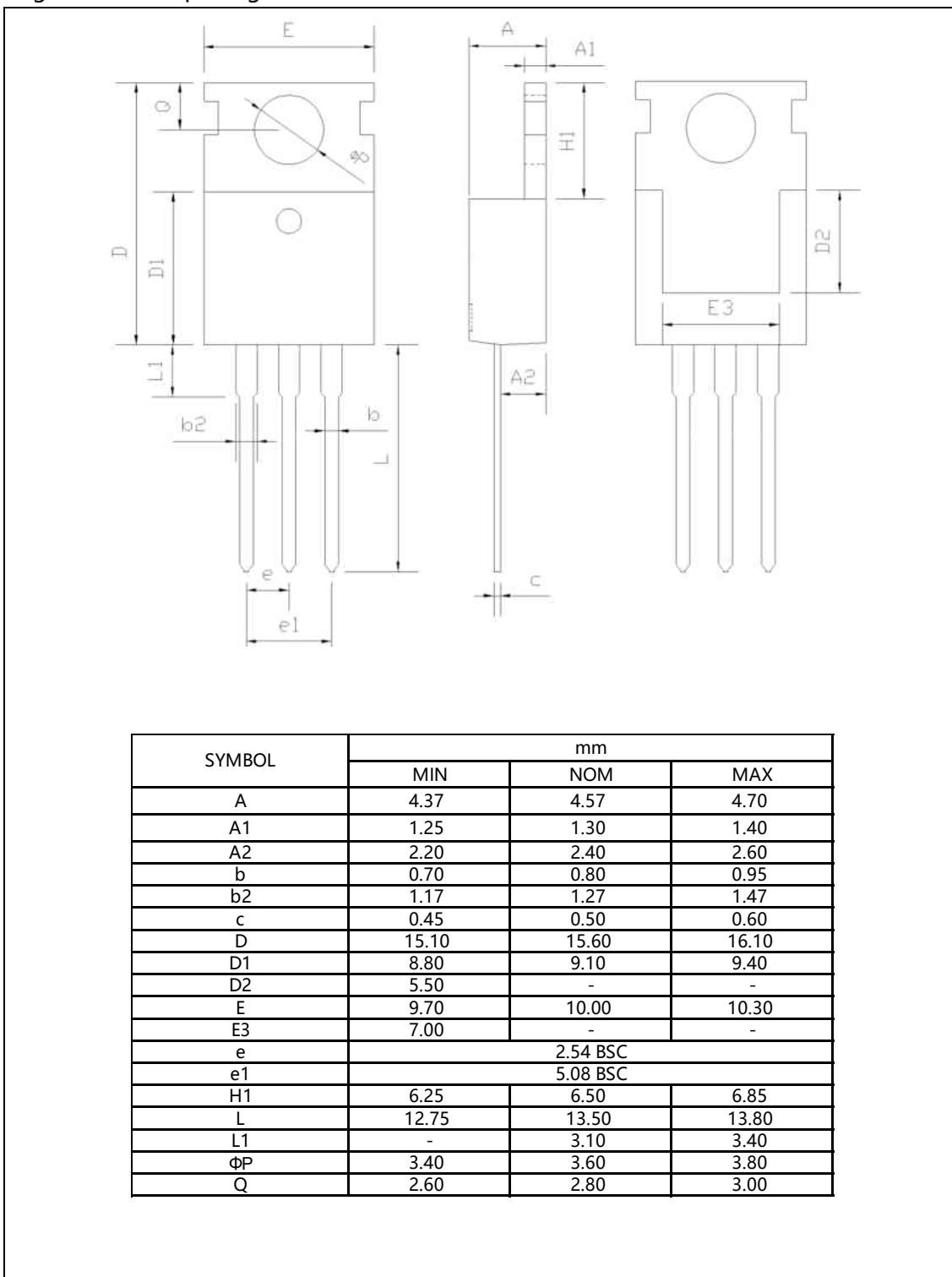
Figure3, TO220F package outline dimension





## ■ Package Information

Figure4, TO220 package outline dimension



**■ Ordering Information**

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| Package | Units/Tube | Tubes/Inner Box | Units/Inner Box | Inner Box/Carton Box | Units/Carton Box |
|---------|------------|-----------------|-----------------|----------------------|------------------|
| TO251   | 75         | 66              | 4950            | 6                    | 29700            |
| TO220F  | 50         | 20              | 1000            | 6                    | 6000             |
| TO220   | 50         | 20              | 1000            | 6                    | 6000             |

| Package | Units/Tape | Tapes/Inner Box | Units/Inner Box | Inner Box/Carton Box | Units/Carton Box |
|---------|------------|-----------------|-----------------|----------------------|------------------|
| TO252   | 2500       | 2               | 5000            | 5                    | 25000            |

**■ Product Information**

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| Product     | Package | Pb Free | RoHS | Halogen Free |
|-------------|---------|---------|------|--------------|
| OSG50R1K5AF | TO251   | yes     | yes  | yes          |
| OSG50R1K5DF | TO252   | yes     | yes  | yes          |
| OSG50R1K5FF | TO220F  | yes     | yes  | yes          |
| OSG50R1K5PF | TO220   | yes     | yes  | yes          |